



# **PRODUCT DATASHEET**



- ► Natural White 5000K

# NOW56S33 (CRI 90)





# **APPLICATIONS:**

- **General Lighting** •
- **Portable Lighting**
- **Commercial Lighting** •
- Indoor Lighting •
- Architecture Lighting
- High Bay Light

# 3535 Ceramic Series Compliant

# **FEATURES:**

- Package: Top View Ceramic Package
- Forward Current: 350~1000mA
- Forward Voltage (typ.): 2.9V
- Luminous Flux (typ.): 156lm@350mA .
- Colour: Natural White
- Colour Temperature (typ.): 5000K .
- Viewing Angle: 120°
  - Materials:
    - Die: InGaN \_
    - Resin: Silicon (Yellow Diffused) \_
    - Package: Ceramic
- Operating Temperature: -40~+105°C
- Storage Temperature: -40~+85°C
- Electrostatics Discharge: 1000V
  - **Grouping Parameters:** 
    - **Forward Voltage** \_
    - \_ Luminous Flux
    - **CIE Chromaticity** \_
- Soldering Methods: Reflow Soldering
- MSL Level: MSL3 according to J-STD020
- Packing: 12mm tape with max.900/reel, ø165mm (6.5")





# CHARACTERISTICS:

#### Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	IF	1000	mA
Pulse Forward Current (Duty 1/10, width≤100µS)	Ipf	1500	mA
Power Dissipation	PD	3400	mW
Reverse Voltage	VR	5	V
Reverse Current @10V	IR	10	μΑ
Junction Temperature	Tj	125	°C
Electrostatic Discharge	ESD	1000	V
Thermal Resistance (Junction to Solder Point)	Rth(j-sp)	5	°C/W
Operating Temperature	T <sub>OPR</sub>	-40~+105	°C
Storage Temperature	Тѕтб	-40~+85	°C
Soldering Temperature	T <sub>SOL</sub>	230/260 for 10S	°C
Colour Rendering Index	CRI	min. 90 typ. 92	

1. Rth(j-sp) is the thermal resistance from LED junction to solder point on MCPCB with electrical power.



# **CHARACTERISTICS:**

Daramatar			Values		Unit	Test	
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition	
Forward Voltage	VF	2.6	2.9	3.4	V	I⊧=350mA	
Luminous Flux		130	156		Im	I <sub>F</sub> =350mA	
(Tj=25°C)	Φv		289		1111	I⊧=700mA	
Luminous Flux (Tj=85°C)	Φν		140		Im	I <sub>F</sub> =350mA	
			257		1111	I⊧=700mA	
Chromaticity	х	0.3361		0.3571		l⊧=350mA	
Coordinates	Y	0.3245		0.3907		I⊦−SOUIIA	
Colour Temperature	ССТ		5000		к	I⊧=350mA	
Viewing Angle	20 <sub>1/2</sub>		120		deg	I⊧=350mA	

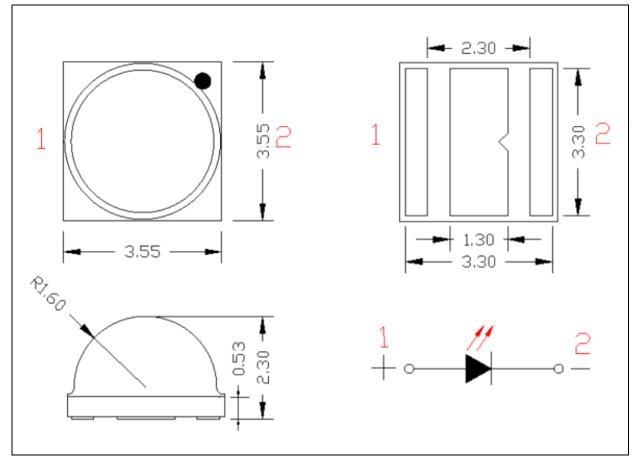
#### Electrical & Optical Characteristics (Ta=25°C)

1. Luminous flux ( $\Phi_V$ ) ±10%, Forward Voltage (V\_F) ±0.1V, CRI ±2

# **OUTLINE DIMENSION:**

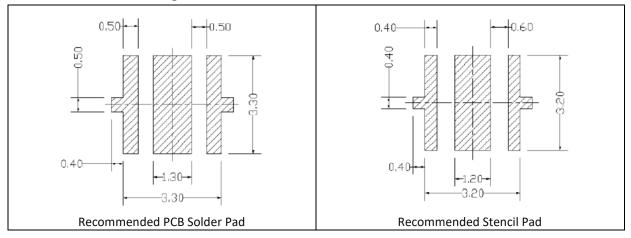


#### Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

#### Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance  $\pm 0.1$ mm with angle tolerance  $\pm 0.5^{\circ}$ .



#### **BINNING GROUPS:**

Code	Min.	Max.	Unit
G3	2.6	2.8	
H3	2.8	3.0	V
J3	3.0	3.2	V
К3	3.2	3.4	

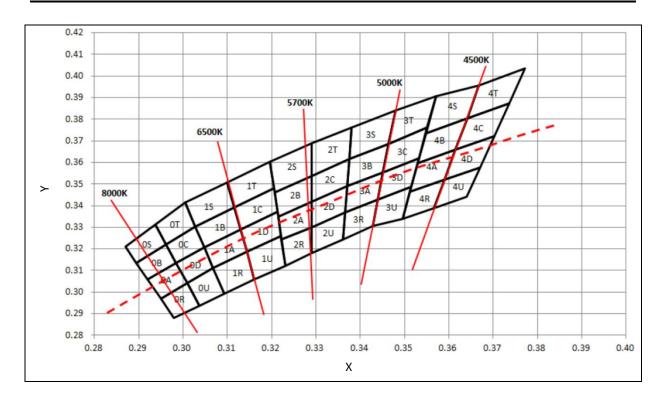
#### Forward Voltage Classifications (I<sub>F</sub> = 350mA):

#### Luminous Flux Classifications (I<sub>F</sub> = 350mA):

Code	Min.	Max.	Unit
2F	130	139	
2G	139	148	
2Н	148	156	lm
2J	156	164	
2К	164	172	



# **CIE CHROMATICITY DIAGRAM:**

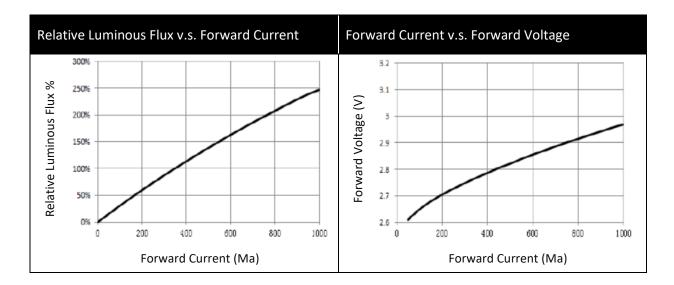


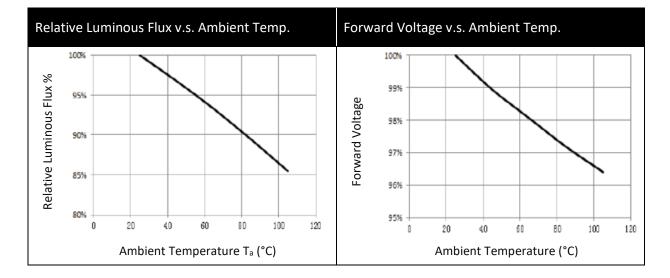
#### Chromaticity Coordinates Classifications (I<sub>F</sub> = 350mA):

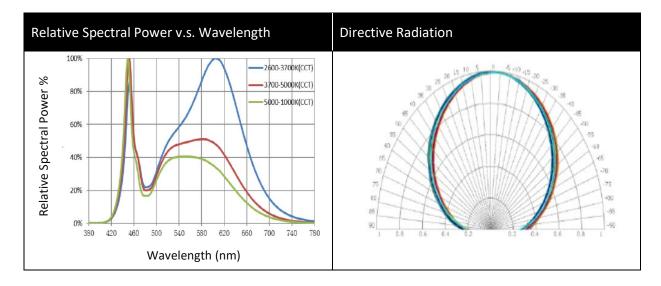
	<u>í</u>	L	2		3		4	
	х	Y	Х	Y	Х	Y	Х	Y
3A	0.3371	0.3490	0.3451	0.3554	0.3440	0.3427	0.3366	0.3369
3B	0.3376	0.3616	0.3463	0.3687	0.3451	0.3554	0.3371	0.3490
3C	0.3463	0.3687	0.3551	0.3760	0.3533	0.3620	0.3451	0.3554
3D	0.3451	0.3554	0.3533	0.3620	0.3515	0.3487	0.3440	0.3427
3R	0.3366	0.3369	0.3440	0.3428	0.3429	0.3307	0.3361	0.3245
35	0.3381	0.3762	0.3480	0.3840	0.3463	0.3687	0.3376	0.3616
3T	0.3480	0.3840	0.3571	0.3907	0.3551	0.3760	0.3463	0.3687
3U	0.3440	0.3428	0.3515	0.3487	0.3495	0.3339	0.3429	0.3307



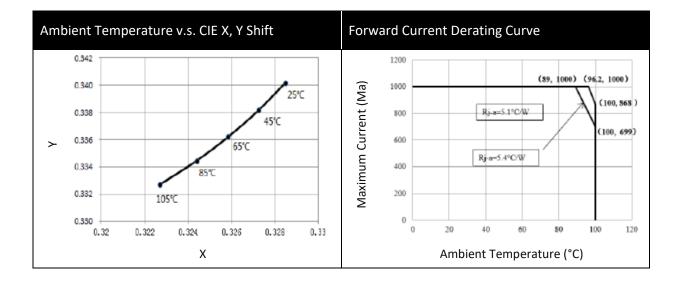
# **ELECTRO-OPTICAL CHARACTERISTICS:**





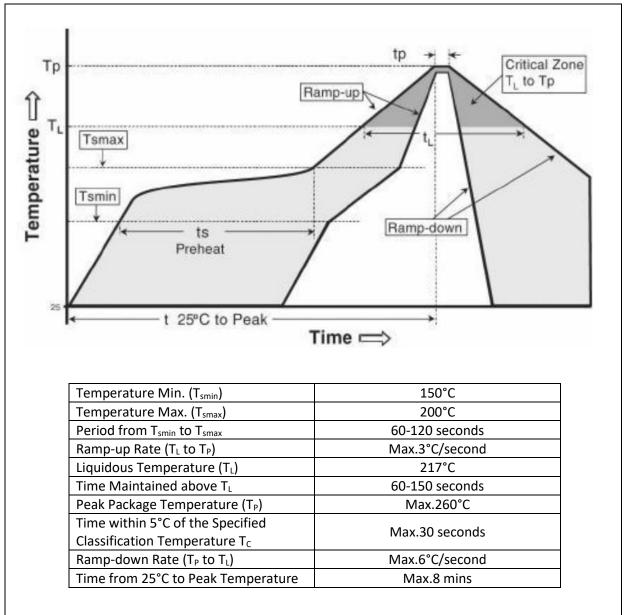








## **RECOMMENDED SOLDERING PROFILE:**



Reflow Lead-free Solder:

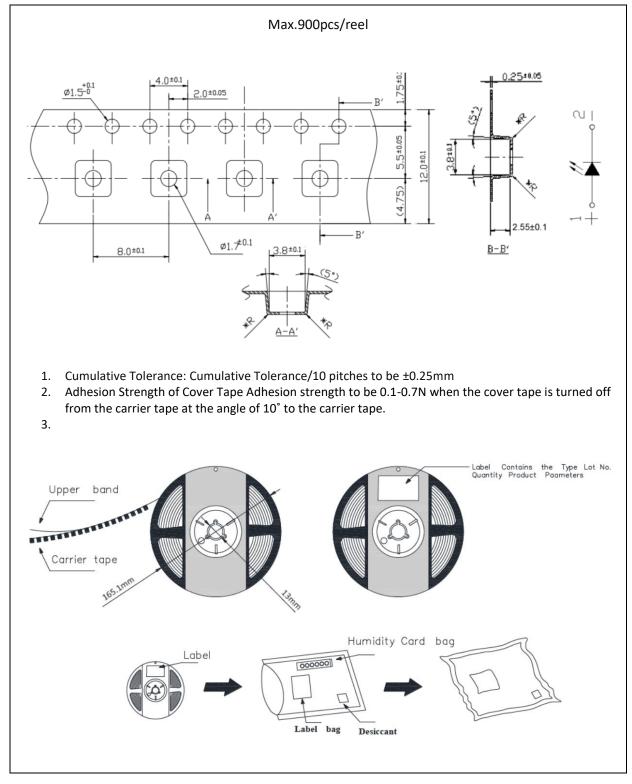
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.
- 3. Recommended soldering temperature: 240°C. The maximum soldering temperature should be limited to 260°C for max. 10seconds.



# **PACKING SPECIFICATION:**

#### Reel Dimension:



## **PRECAUTIONS OF USE:**



#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

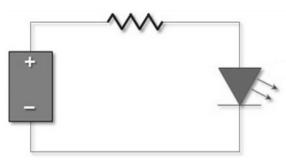
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

#### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

#### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



# **REVISION RECORD:**

Version	Date	Summary of Revision		
A1.0	24/09/2020	Datasheet set-up.		
A1.1	22/03/2022	New datasheet format.		
A1.2	23/03/2022	Revise temperature range.		
A1.3	07/09/2023	Revised bin table.		
A1.4	03/03/2024	Add 700mA typical lumen information.		